
EMAC PCB & Assembly Requirements – R1

- **Solder Mask Color:** _____
 - (default: Green)

- **Silkscreen Color:** _____
 - (default: White)

- **Board Finish:** _____
 - (default: ENIG)

- **Impedance Control:** _____
 - (default: No)

- **Customer Specific Requirements:** _____
 - (IPC Class 3, UL, Wash Restrictions, etc.; default: Not Required)

- **Materials Requirements:** _____
 - (default: Core material in accordance with IPC-4101C/126, laminated sheet, woven E-glass, Tg of 170 minimum, flame resistant UL 94V-0, RoHS Compliant)
 - (default: Pre-Preg material in accordance with IPC-4101C/126, woven E-glass Tg of 170C minimum, flame resistant UL 94V-0, RoHS compliant)

- **Layer Registration:** _____
 - (default: Layer-to-layer registration must not be more than 3.0 mil from layer 1)

- **Drill Requirements:** _____
 - (default: All drill data is finished size)
 - (default: Finished drill locations shall be within 4.0 mil of the specified location)
 - (default: Hole location shall not exceed 2.0 mil from dill file locations)

- **Plated Through Holes:** _____
 - (default: Plated through holes shall have a minimum average copper thickness of 1.0 mil with an absolute minimum of 0.7 mil. for 1oz copper. For other copper weights contact EMAC for defaults.)

- **Conformal Coating:** _____
 - (default: RTV Silicone - Dow Corning 1-2577)

Note: EMAC is not responsible for incorrect fabrication of the PCB if the PCB requirements are incorrect or missing. If possible, it is recommended that the customer perform a small test run in order to validate the correct PCB fabrication and the Assembly Process.